

Feature

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$

Product Summary

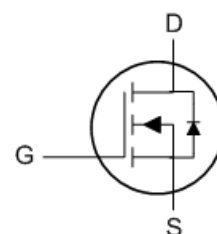
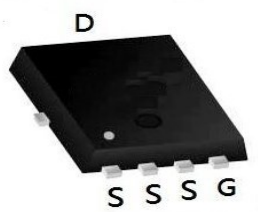


BVDSS	RDSON	ID
100V	6.2mΩ	75A

Application

- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

PDFN5060-8L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	±20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	75	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	51	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	320	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	150	mJ
$I_{AS}$	Avalanche Current	---	A
$P_D@T_C=25^\circ C$	Total Power Dissipation <sup>4</sup>	108	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	1.15	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	60	°C/W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	100	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	---	---	V/°C
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	---	6.2	7.75	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	---	7.6	8.36	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.3	1.8	2.3	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	---	---	mV/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =100V, V <sub>GS</sub> =0V, T <sub>J</sub> =100°C	---	---	---	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =15A	---	---	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	0.65	---	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =50V, V <sub>GS</sub> =10V, I <sub>D</sub> =20A	---	32.1	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	9.7	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	8.6	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =50V, I <sub>D</sub> =20A, R <sub>G</sub> =4Ω, V <sub>GS</sub> =10V	---	15	---	ns
T <sub>r</sub>	Rise Time		---	23	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	45	---	
T <sub>f</sub>	Fall Time		---	35	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V, f=1MHz	---	1916	---	pF
C <sub>oss</sub>	Output Capacitance		---	602	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	17	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,4</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	75	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =20A, T <sub>J</sub> =25°C	---	---	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =20A, di/dt=100A	---	60	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge	/ μs, T <sub>J</sub> =25°C	---	110	---	nC

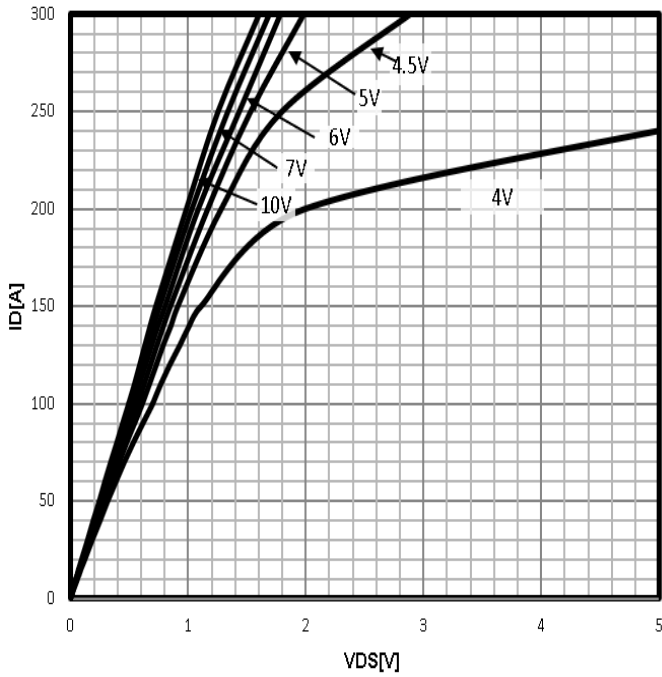
<sup>a1</sup>: Repetitive rating; pulse width limited by maximum junction temperature

<sup>a2</sup>: V<sub>DD</sub>=50V, L=0.3mH, R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25 °C

Characteristics Curve:

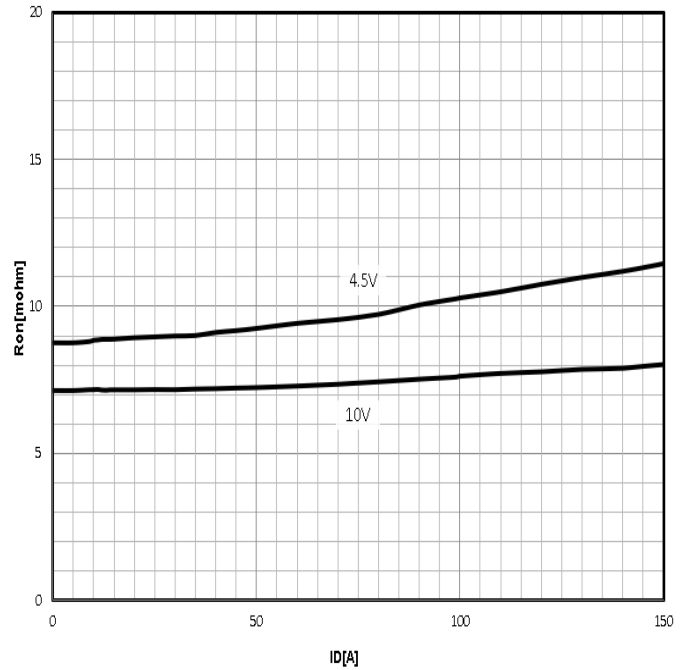
Typ. output characteristics

$I_D=f(V_{DS})$



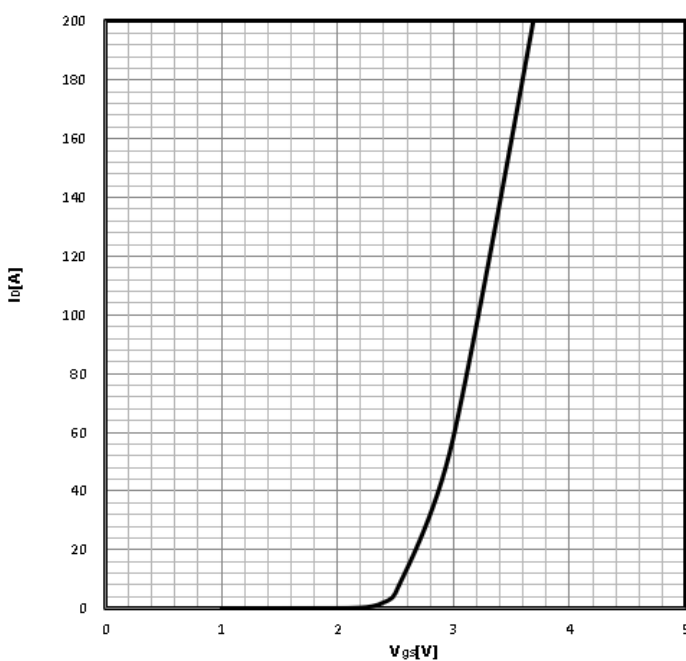
Typ. drain-source on resistance

$R_{DS(on)}=f(I_D)$



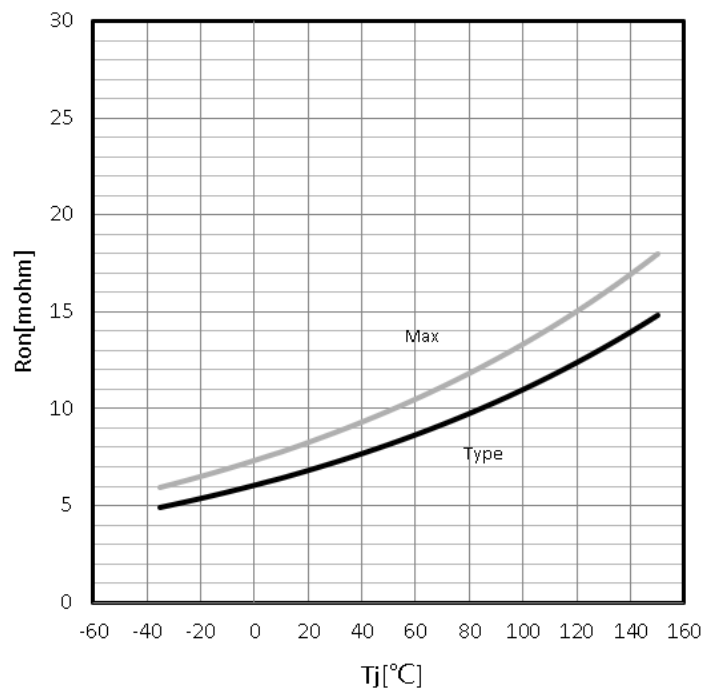
Typ. transfer characteristics

$I_D=f(V_{GS})$

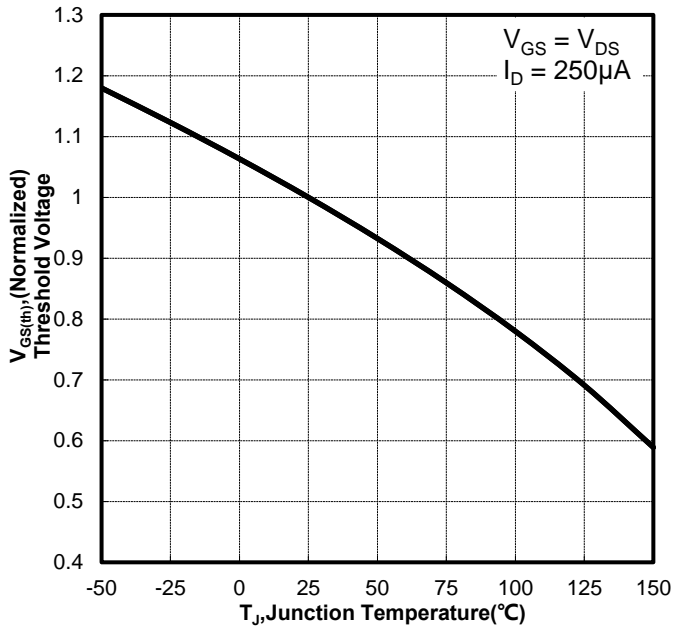


Drain-source on-state resistance

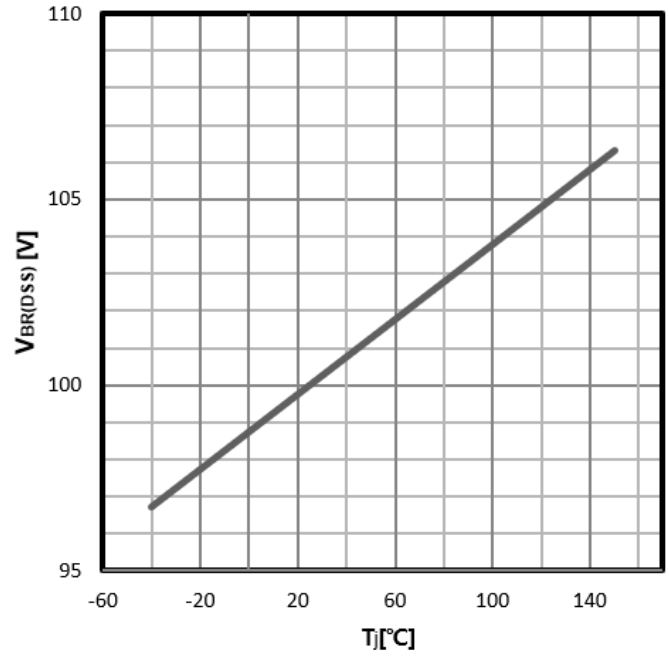
$R_{DS(on)}=f(T_j); I_D=20A; V_{GS}=10V$



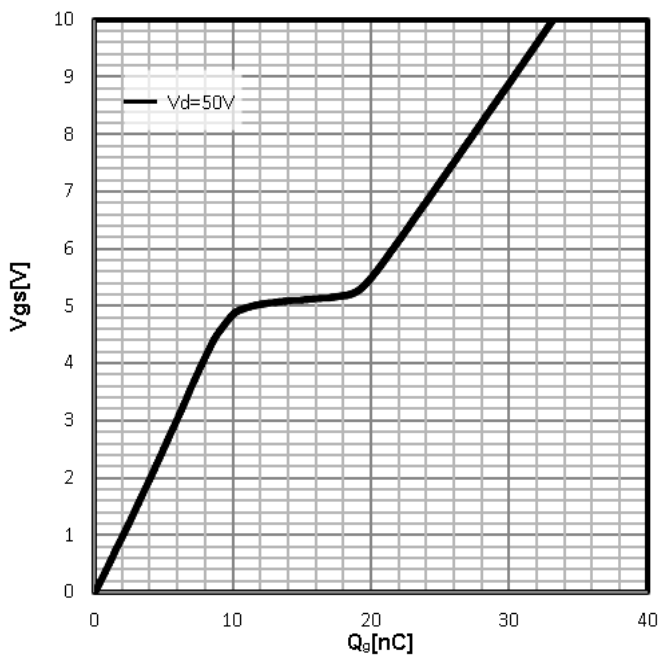
**Gate Threshold Voltage**  
 $V_{TH}=f(T_j); I_D=250\mu A$



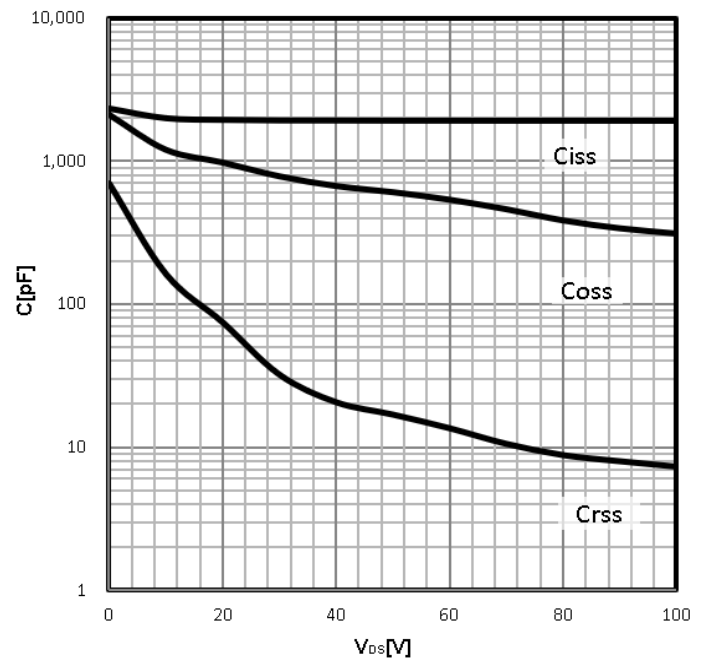
**Drain-source breakdown voltage**  
 $V_{BR(DSS)}=f(T_j); I_D=250\mu A$



**Typ. gate charge**  
 $V_{GS}=f(Q_g); I_D=20A$

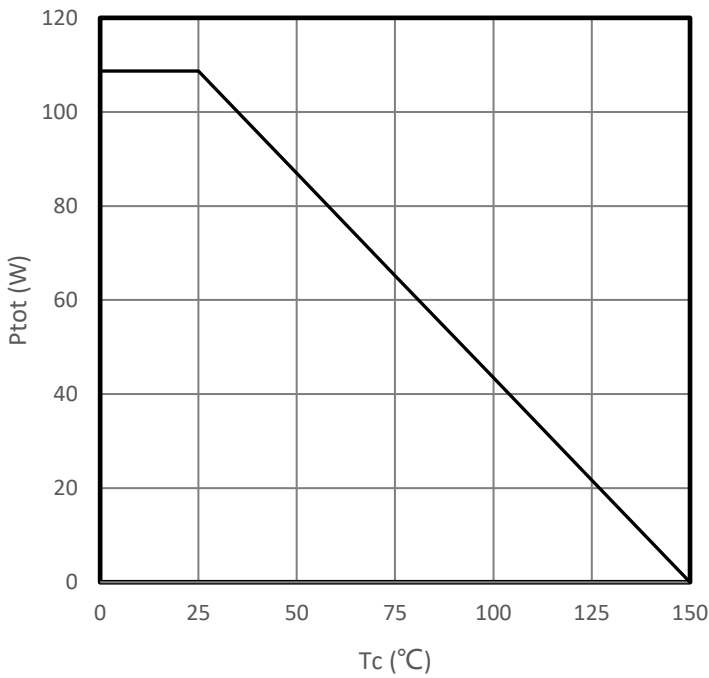


**Typ. capacitances**  
 $C=f(V_{DS}); V_{GS}=0V; f=1MHz$

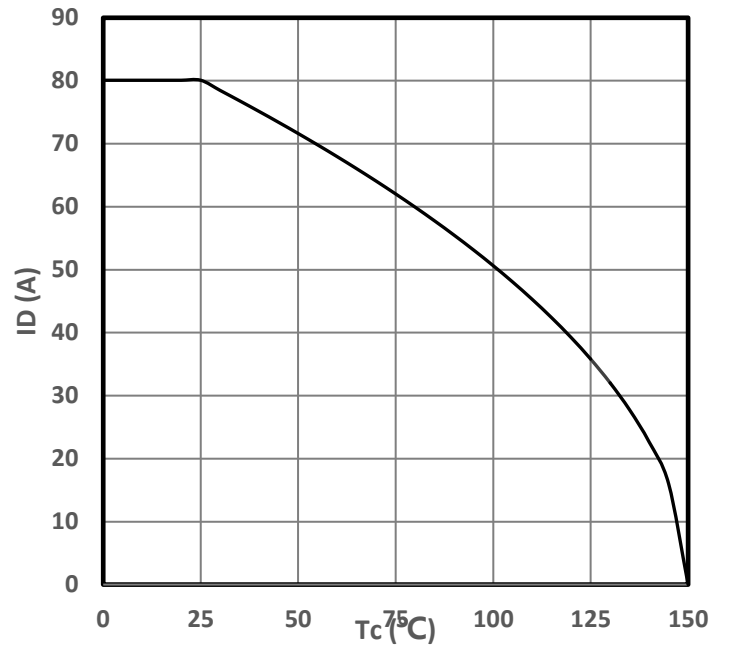


N-Ch 100V Fast Switching MOSFETs

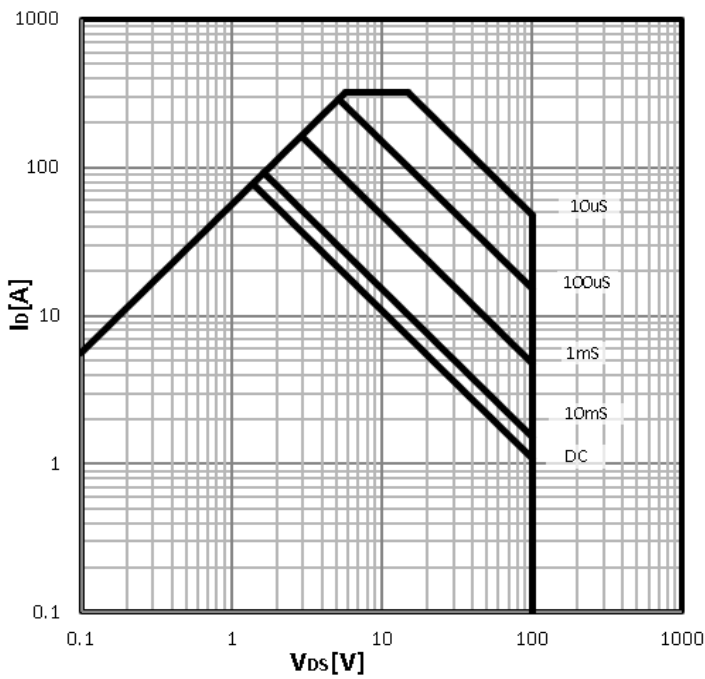
**Power Dissipation**  
 $P_{tot}=f(T_C)$



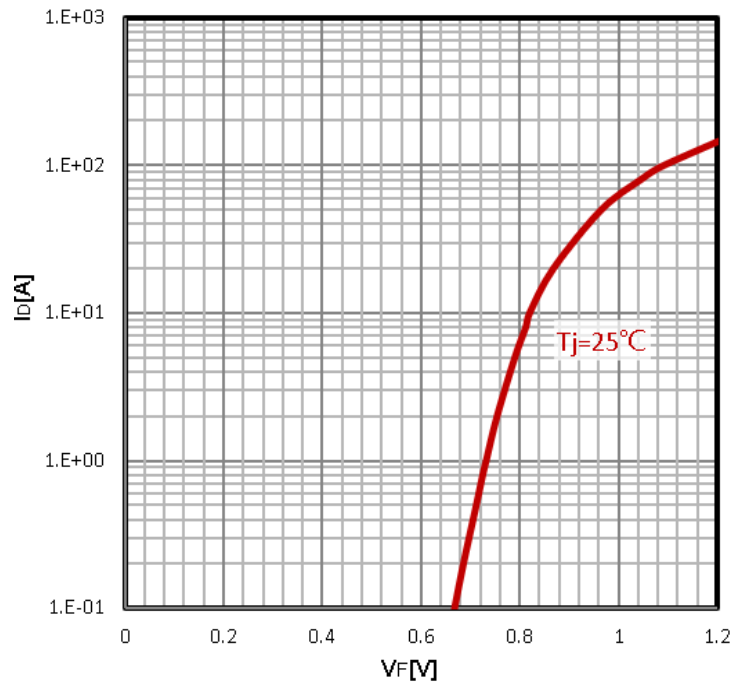
**Maximum Drain Current**  
 $I_D=f(T_C)$



**Safe operating area**  
 $I_D=f(V_{DS})$

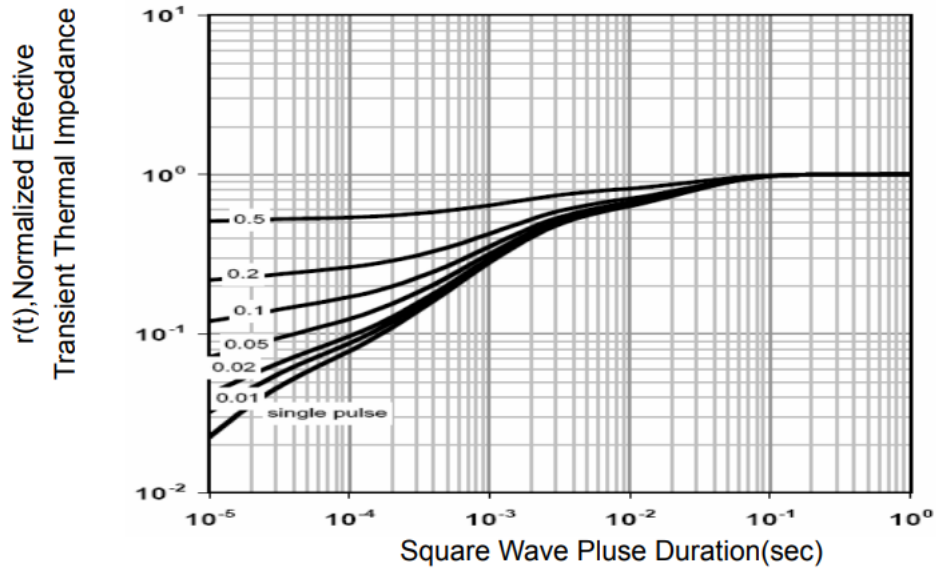


**Body Diode Forward Voltage Variation**  
 $I_F=f(V_{GS})$

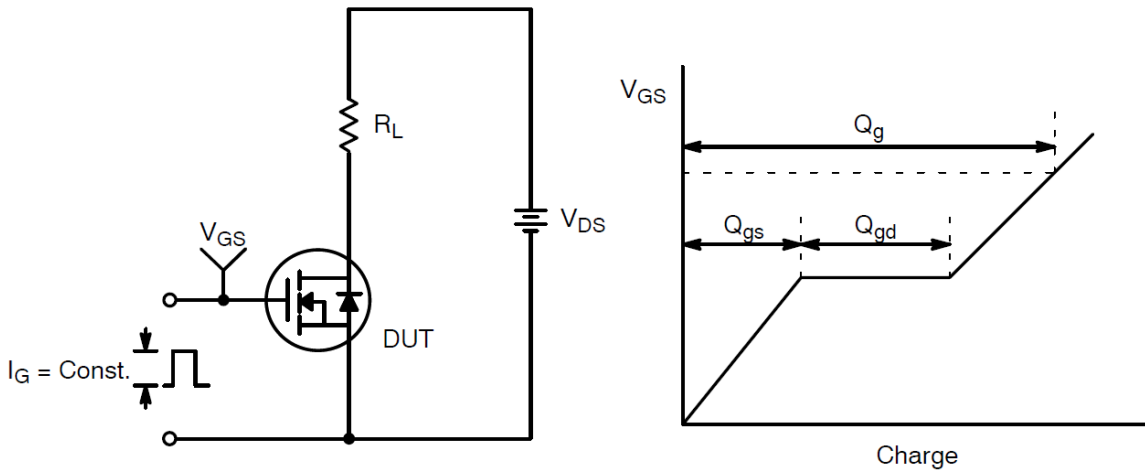


Max. transient thermal impedance

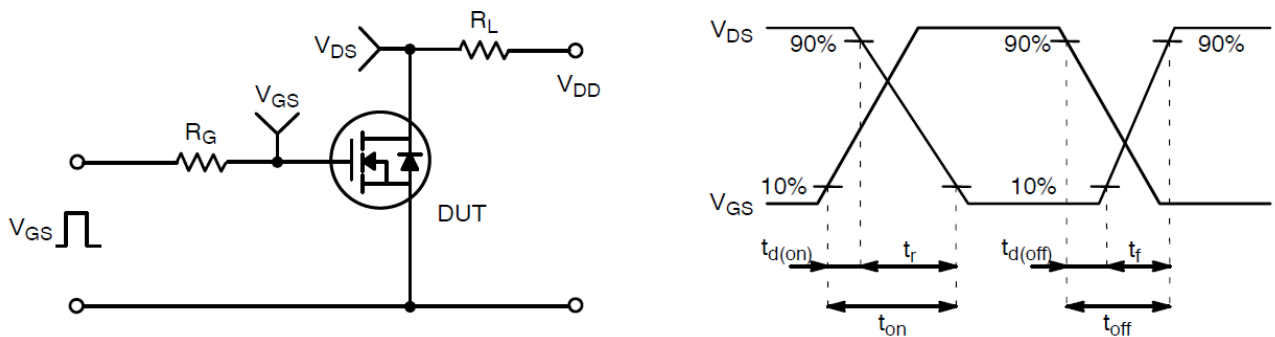
$$Z_{thJC}=f(t_p)$$



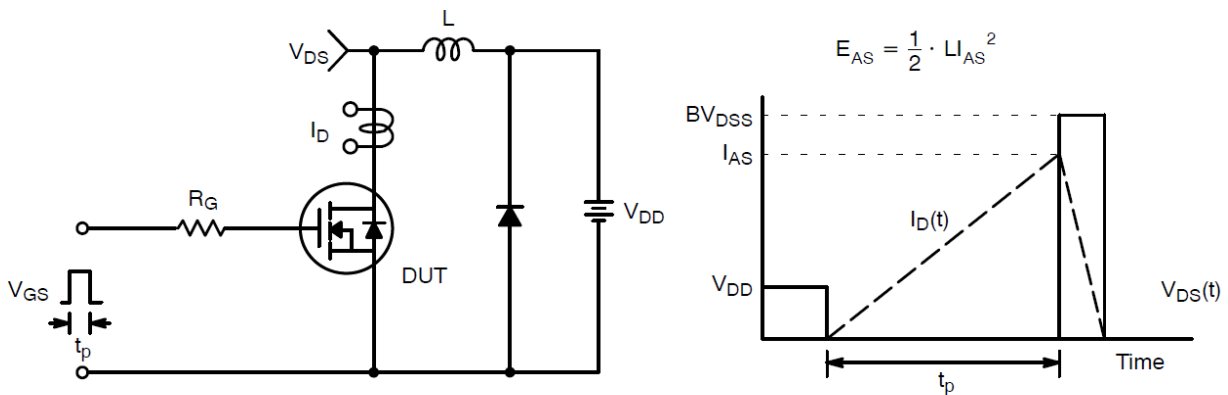
**Test Circuit and Waveform:**



**Gate Charge Test Circuit & Waveform**

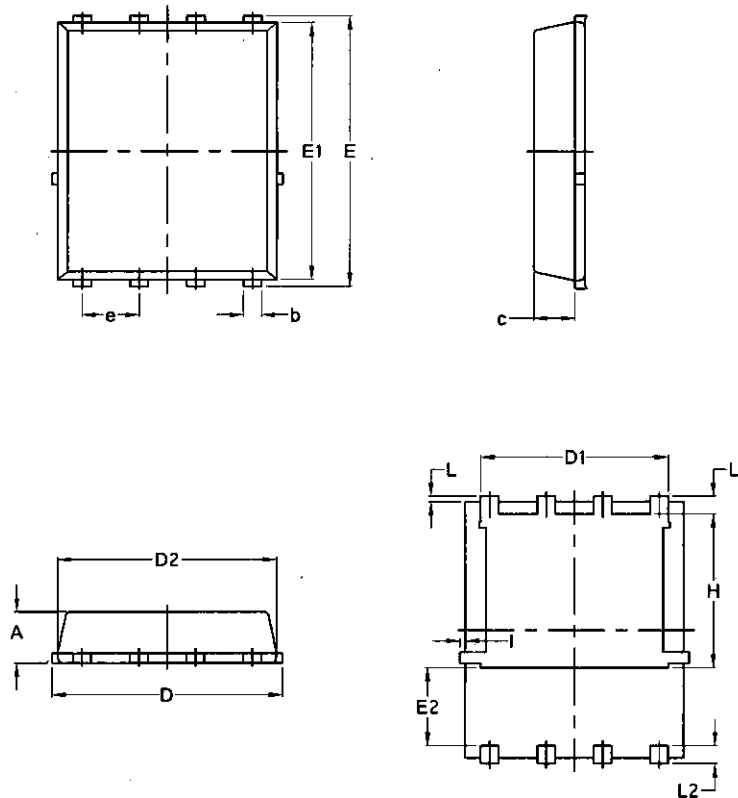


**Resistive Switching Test Circuit & Waveforms**



**Unclamped Inductive Switching Test Circuit & Waveforms**

Package Mechanical Data-PDFN5060-8L-Single



Symbol	Common			
	mm		Inch	
	Min	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070